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PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10073876	FILING DATE 02/14/2002	CLASS 414	SUBCLASS 783	GAU 3651	EXAMINER Kvizek
**APPLICANTS: Osaka Akihiro; Sekiyama Hiroshi; Noto Kouichi; Sugawara Masaki;					
**CONTINUING DATA VERIFIED: THIS APPLICATION IS A DIV OF 09/544,463 04/07/2000, Pat No. 6,368,049					
** FOREIGN APPLICATIONS VERIFIED: JAPAN 11-99562 04/07/1999					
PG-PUB <input type="checkbox"/> DO NOT PUBLISH <input type="checkbox"/>		RESCIND <input type="checkbox"/>			
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no 35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no Verified and Acknowledged Examiners's initials				ATTORNEY DOCKET NO 105913.01	
TITLE : Semiconductor manufacturing method and semiconductor manufacturing apparatus <small>U.S. DEPT. OF COMM./PAT. & TM-PTO-436L (Rev. 12-94)</small>					

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claim for O.G.
ISSUE FEE		DRAWING	
Amount Due	Date Paid	Sheets Drwg.	Figs. Drwg. Print Fig.
		Application Examiner	
<input type="checkbox"/> TERMINAL DISCLAIMER		PREPARED FOR ISSUE	
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